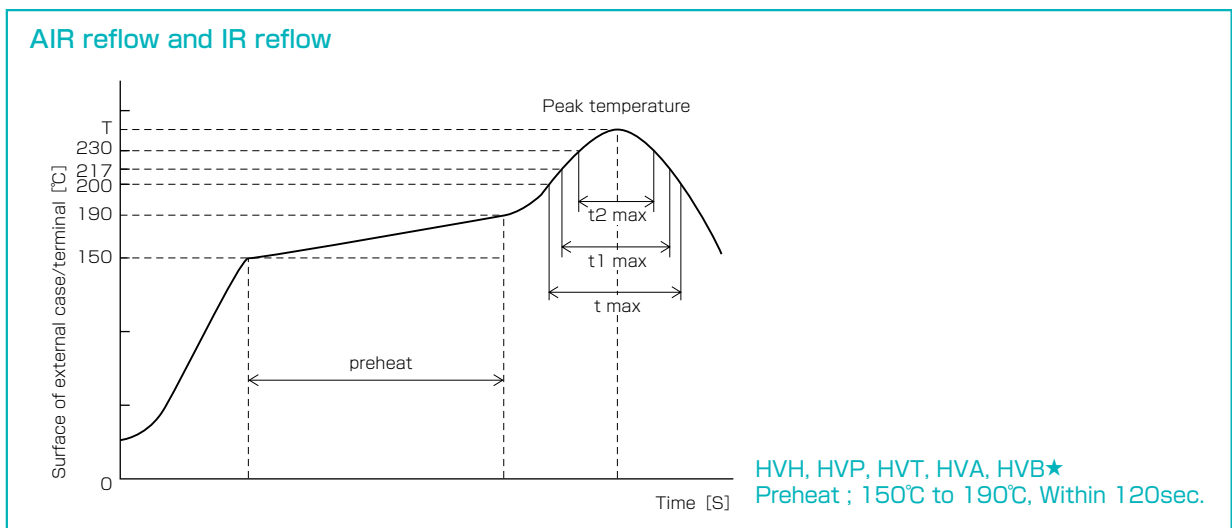


Soldering Condition / Recommended Reflow Condition / Ripple Current Frequency Coefficient

■ Soldering Condition

- Soldering with a soldering iron - within 350°C×3 seconds unless otherwise specified in the spec.
- Flow soldering - within 260°C×10 seconds unless otherwise specified in the spec.
(Do not apply flow soldering to SMD type.)
- Thermal curing over - ambient temperature within 150°C×2 minutes.

■ Recommended Reflow Condition



Series	Voltage (V)	Size	Time of more than 200°C (t)	Time of more than 217°C (t1)	Time of more than 230°C (t2)	Peak temperature (Within 5sec.)
HVA,HVB★	6.3 to 16	ALL	Within 100sec.	Within 80sec.	Within 40sec.	250°C
HVH,HVP,HVT	25 to 63	φ6.3×4.5	Within 60sec.	Within 50sec.	Within 30sec.	250°C
		φ6.3×6.0 to φ10	Within 100sec.	Within 80sec.	Within 40sec.	260°C
	80 to 125	ALL	Within 100sec.	Within 80sec.	Within 40sec.	250°C

Capacitors can withstand two reflow processes on the above conditions. Second reflow shall be taken after more than one hour natural cooling time and taken after the return to normal temperatures of PCB board and components.

■ Ripple Current Frequency Coefficient

Series	Capacitance : C (μF)	Frequency : F (Hz)			
		100 ≤ F < 1k	1k ≤ F < 10k	10k ≤ F < 100k	100k ≤ F < 500k
HVH, HVP HVT, HEH	C ≤ 4.7	0.03	0.30	0.65	1.00
	4.7 < C ≤ 33	0.05	0.32	0.67	1.00
	33 < C	0.10	0.35	0.70	1.00
HVA, HVB★ HEA★	C ≤ 10	0.03	0.20	0.50	1.00
	10 < C	0.05	0.20	0.50	1.00

■ Anti-vibration structure

Available for φ8 and φ10.
[Type code]

Standard structure	Anti-vibration structure
HV	HA

Please refer to <http://www.sunelec.co.jp> for the information in columns where ★ marking is indicated in a page row.

Basic Construction
Features / Applications
Product Line-up Table

Characteristics

Advantages of EP-cap

Soldering Condition
Recommended Reflow Condition
Ripple Current Frequency Coefficient

HVA
HVH
HVP
HVT
HEH